

❖ **Features:**

- 2.1mm x 0.6mm SMT LED, 1.0mm thickness
- Mono-color type
- Soldering methods :All SMT assembly methods
- Comply ROHS standard



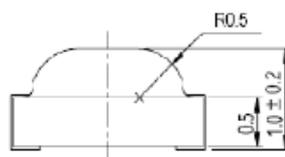
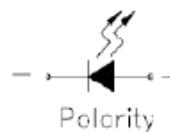
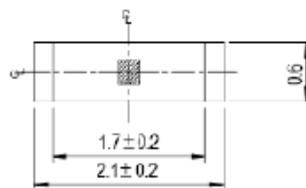
❖ **Description**

The Yellow Green source color devices are made with **AlGaInP** on sapphire Light Emitting Diode.

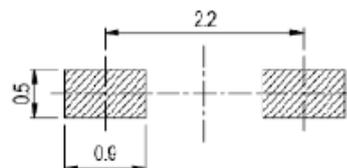
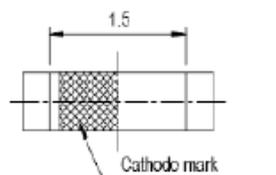
❖ **Application**

- Optical indicator
- Indicator and backlighting in telephone and fax
- Flat backlight for LCD, switch and symbol
- Light pipe application
- General use

❖ **Package Dimensions**



For reflow soldering (Propose)



NOTES:

1. All dimensions are in millimeter[unit];
2. Tolerance is $\pm 0.1\text{mm}$ (0.004 ") especially other specified;
3. Specifications are subject to change without notice.

Emitted Color	Len's Color	Chip Material
Yellow Green	Water Clear	AlGaInP

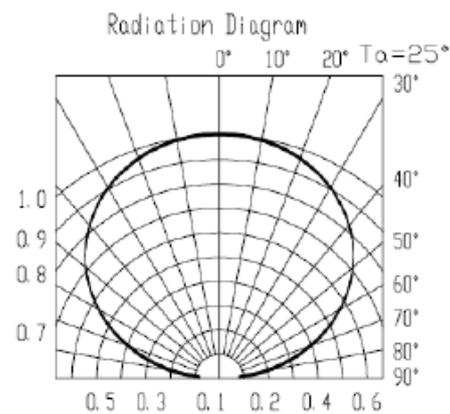
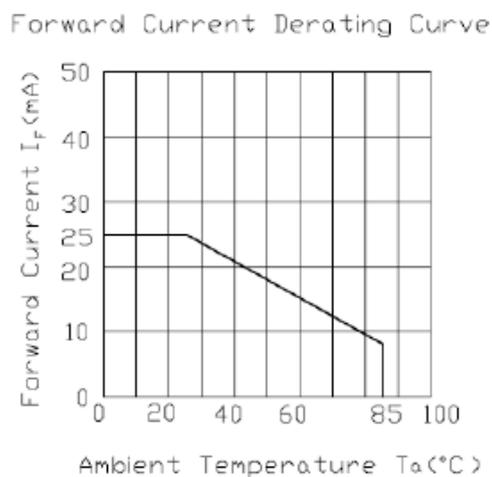
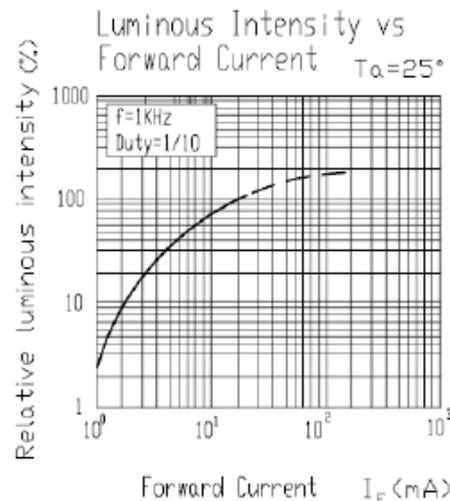
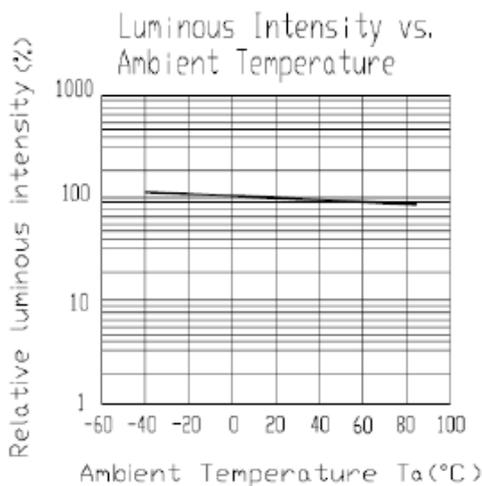
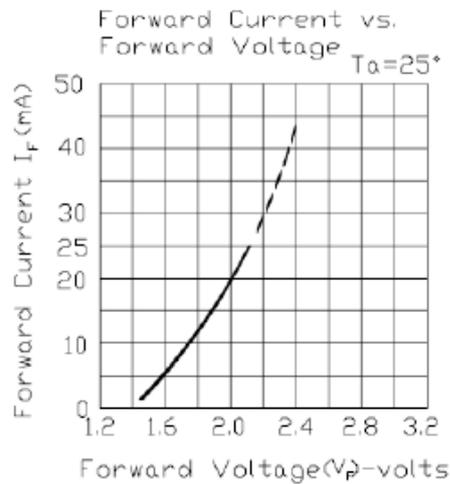
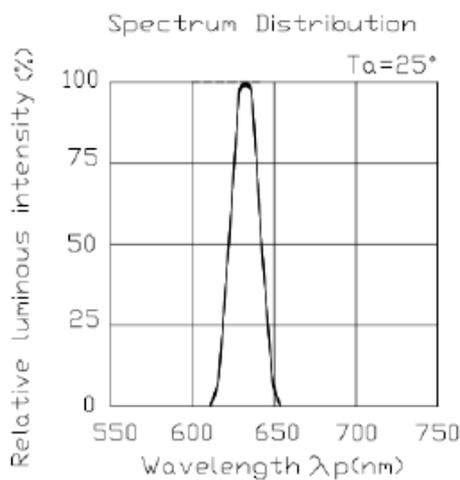
◇ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Item	Symbol	Maximum	Unit
Power Dissipation	PD	60	mW
Continuous Forward Current	I_{Fmax}	30	mA
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse Width)	I_{FP}	70	mA
Reverse Voltage	V_R	5	V
Operating Temperature Range	T_{opr}	-40 to+85	25°C
Storage Temperature Range	T_{stg}	-40 to+85	25°C

◇ Electrical/Optical Characteristics($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	Min.	Typ.	Max	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	1.8	2.0	2.2	V
Luminous Intensity	I_V	$I_F=20\text{mA}$	10	30	55	mcd
Wavelength	λ	$I_F=20\text{mA}$	573	--	575	nm
Typical Correlated Color Temperature	T_c	$I_F=20\text{mA}$	--	---	--	K
Chromaticity Coordinates	X	$I_F=20\text{mA}$	--	--	--	--
	Y	$I_F=20\text{mA}$	--	--	--	--
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	--	130	--	Deg
Capacitance	C	$V_F=0\text{V}, f=1\text{MHz}$	--	45	--	pF
Reverse Current	IR	$V_R=5\text{V}$	--	5	10	μA

❖ Typical Electro-Optical Characteristics Curves

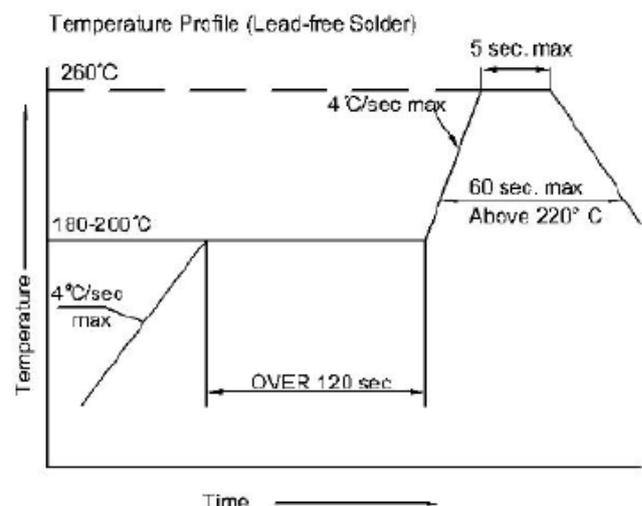
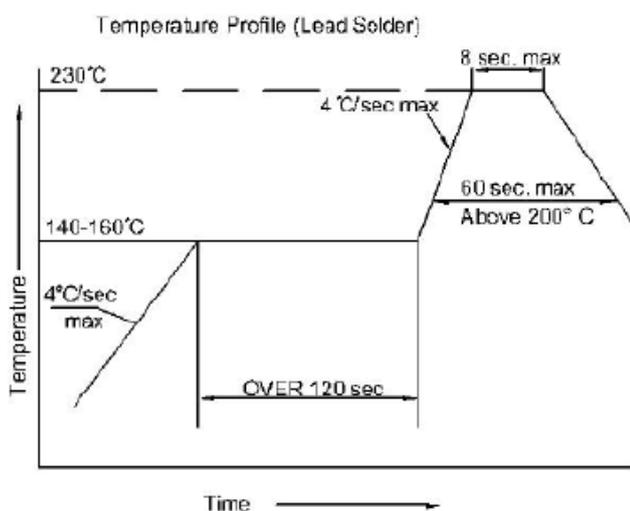


❖ Reliability Test Items And Conditions

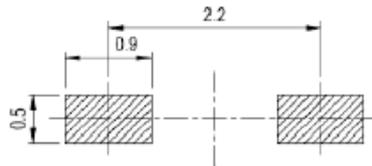
NO.	Item	Test Condition	Test Hr/cycle/time	Sample Q'ty	Ac/Re
1	Reflow	TEMP:260±5°C; Min.5Sec	6 min	22pcs	0/1
2	Temperature Cycle	H:+100°C 15mins To(5mins) L:-40°C 15mins	300 cycles	22pcs	0/1
3	Thermal Shock	H:+100°C 15mins To(5mins) L:-40°C 15mins	300 cycles	22pcs	0/1
4	High Temperature Storage	TEMP:+260°C	1000hrs	22pcs	0/1
5	Low Temperature Storage	TEMP:-40°C	1000hrs	22pcs	0/1
6	DC Operating Life	IF=20MA	1000hrs	22pcs	0/1
7	High Temperature	85°C	1000hrs	22pcs	0/1
8	High Humidity	85%R.H.	1000hrs	22pcs	0/1

❖ SMT Reflow Soldering Instructions

Number of reflow process shall be than 2 times and cooling
Process to normal temperature is required between first and second
soldering process



❖ Recommended Soldering Pad Dimensions



❖ Tape Specification: 3,000PCS per reel

